

REMARKS

Claims 1-4 are pending in the application. Claim 1 has been amended to indicate that the mount substrate has unevenness due to components on its surface. Claims 2 and 3 have been amended to read in independent form. The amendments are supported at, for example, the original claims and at page 5, lines 7-11 of the specification. The specification has been amended to correct an obvious typographical error. It is also acknowledged that allowable subject matter has been indicated in claims 2 and 3.

Claims 1 and 4 stand rejected under 35 U.S.C. § 102(a) as being anticipated by JP 10-302040 to Toke (hereinafter "Toke"). The Examiner asserts that Toke discloses the claimed process.

In Toke, the mounting substrate 11 to be processed is a mounting substrate as shown in Fig. 3. In other words, in the mounting substrate 11, the irregularity of IC 12 and aerial coil 15 are absorbed and smoothed by feeding thermosetting resins 26 on the surface of mounting substrate 11. Thereafter, an exfoliation sheet 27 is laminated on the smooth face of the mounting substrate 11.

Additionally, in Fig. 4 of Toke, a process for producing cards is shown where a front sheathing sheet 32 and a rear sheathing sheet 33 is stuck on both faces of the mounting substrate 11, which has been smoothed using the process shown in Fig. 3. Therefore, Toke always requires that the process shown in Fig. 3 be included in their invention.

Furthermore, in order to use the process that is shown in Fig. 4 of Toke, it is necessary to exfoliate the exfoliation sheet 27 from the mounting substrate 11, requiring a very complicated set of steps in the process.

In presently amended claim 1, the process for producing IC cards includes the steps of continuously feeding a mount substrate with unevenness due to the components on the surface thereof and simultaneously feeding a pair of sheet members on both surface sides of the mount substrate in such a manner that the mount substrate is interposed between the pair of sheet members. An adhesive fluid is fed onto the surface of the sheet members and the distance between the pair of sheet members is maintained at a constant spacing. The adhesive is hardened by interposing the mount substrate between the surfaces of the sheet members on which the adhesive is fed.

Because the process of amended claim 1 does not require the lamination of an exfoliation sheet followed by exfoliating the exfoliation sheet from the mounting substrate as required by Toke, it is not anticipated by Toke. Therefore the rejection of claims 1 and 4 under 35 U.S.C. § 102(a) should be withdrawn.

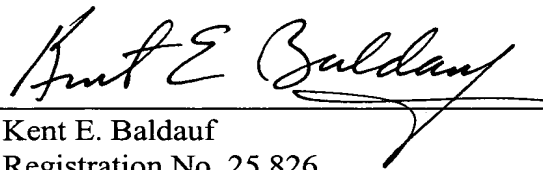
The Examiner indicated that claims 2 and 3 would be allowable if rewritten in independent form including all of the limitations of claim 1. Applicants have complied with this requirement and, accordingly, claims 2 and 3 are now in condition for allowance.

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In view of the above amendments and remarks, it is believed that all of the pending claims are in condition for formal allowance. Reconsideration of the rejections and allowance of claims 1-4 are respectfully requested.

Respectfully submitted,

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